

Features

- Efficiency up to 93%
- 180µA(TYP.) Quiescent Current
- Output Current: Up to 1A
- Internal Synchronous Rectifier
- 1.5MHz Switching Frequency
- Soft Start
- Under-Voltage Lockout
- Short LED Protection
- Open LED Protection
- Thermal Shutdown
- 5-pin Small SOT23-5 Packages
- Pb-Free Package

Applications

- 3AA or 4AA Batteries Powered Flashlight
- 1 Cell Li-Ion Battery Powered Flashlight

General Description

The PAM2804 is a step-down constant current LED driver. When the input voltage down to lower than LED forward voltage, then PAM2804 run into LDO mode.

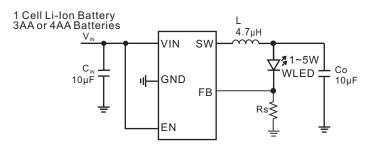
The PAM2804 supports a range of input voltages from 2.5V to 6.0V, allowing the use of a single Li+/Li-polymer cell, 3AA or 4AA cell, USB, and other standard power sources.

The FB voltage is only 0.1V to achieve high efficiency.

PAM2804 employ internal power switch and synchronous rectifier to minimize external part count and realize high efficiency.

During shutdown, the input is disconnected from the output and the shutdown current is less than 1μ A. Other key features include under-voltage lockout to prevent deep battery discharge of the Li+ battery.

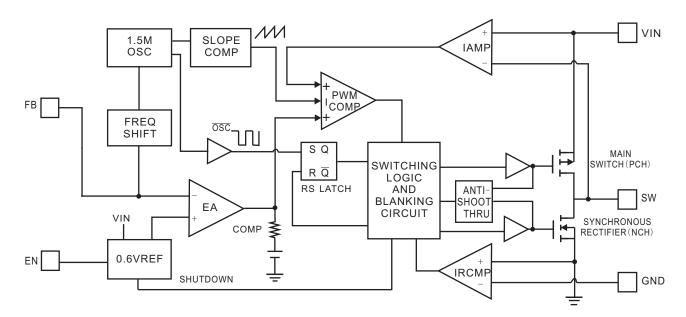
Typical Application



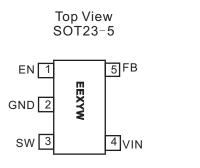
ILED =0.1/Rs



Block Diagram



Pin Configuration & Marking Information





Pin Description

Name	Function
VIN	Chip main power supply pin
GND	Ground
EN	Enable control input. Force this pin voltage above 1.5V, enables the chip, and below 0.3V shuts down the device.
FB	Feedback voltage to internal error amplifier, the threshold voltage is 0.1V.
SW	The drains of the internal main and synchronous power MOSFET.



Absolute Maximum Ratings

These are stress ratings only and functional operation is not implied. Exposure to absolute maximum ratings for prolonged time periods may affect device reliability. All voltages are with respect to ground.

Input Voltage0.3V to 6.5V	Junction Temperature150°C
EN, FB Pin Voltage0.3V to V _{IN}	Storage Temperature Range65°C to 150°C
SW PinVoltage0.3V to $(V_{IN}+0.3V)$	Soldering Temperature300°C, 5sec

Recommended Operating Conditions

Thermal Information

Parameter	Package	Symbol	Maximum	Unit	
Thermal Resistance	SOT23-5 ^{Note}	٥	120		
(Junction to Case)	50123-5	θ _{JC}	130	°C/W	
Thermal Resistance	00702.5	θ _{JA}	250	C/VV	
(Junction to Ambient)	SOT23-5				
Internal Power Dissipation	SOT23-5	P _D	400	mW	

Note:

The maximun output current for SOT23-5 package is limited by internal power dissipation capacity as described in Application Information herein after.



Electrical Characteristic

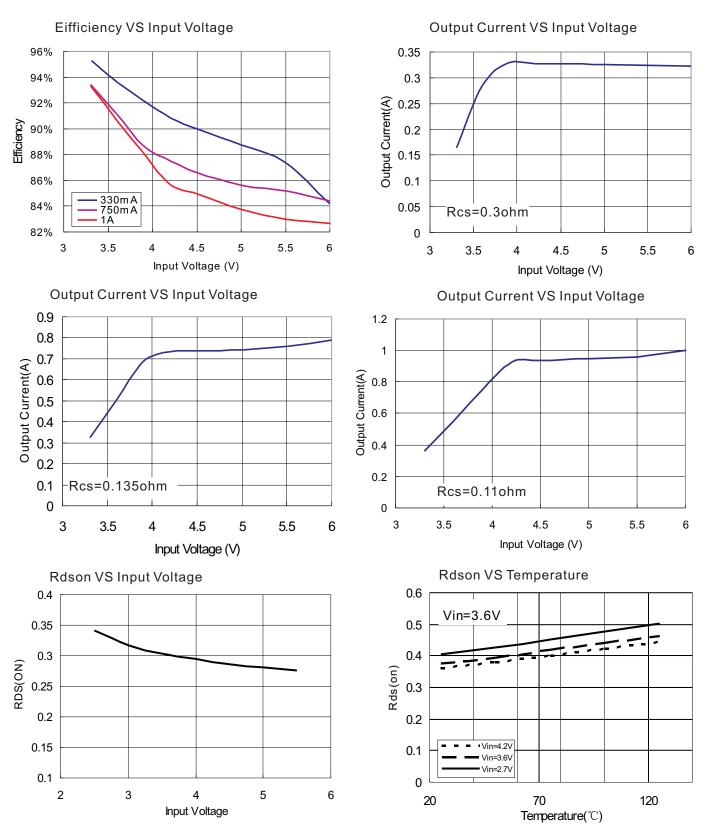
 $T_A=25$ °C, $V_{IN}=4.2V$, Real WLED load, $C_{IN}=10\mu$ F, $C_0=10\mu$ F, L=4.7 μ H, unless otherwise noted.

PARAMETER	SYMBOL	Test Conditions		MIN	ТҮР	MAX	UNITS
Input Voltage Range	V _{IN}			2.5		6.0	V
Regulated Feedback Voltage	V _{FB}			0.095	0.1	0.105	V
Peak Inductor Current	I _{PK}	V _{IN} =5V			1.5		А
Quiescent Current	Ι _Q	No load			180		μA
Shutdown Current	I _{SD}	V _{EN} = 0V				1	μA
Oscillator Frequency	f _{osc}	V _o = 100%		1.2	1.5	1.8	MHz
Drain-Source On-State Resistance	R _{DS(ON)}	I _{DS} =100mA	P MOSFET		0.3	0.45	Ω
Drain-Source On-State Resistance			N MOSFET		0.35	0.5	Ω
SW Leakage Current	I _{LSW}				±0.01	1	μA
High Efficiency	η				93		%
EN Threshold High	V _{EH}			1.5			V
EN Threshold Low	V _{EL}					0.3	V
EN Leakage Current	I _{EN}				±0.01		μA
Over Temperature Protection	OTP				150		°C
OTP Hysteresis	ОТН				30		°C



Typical Performance Characteristics

 $T_A = 25^{\circ}C$, $C_{IN} = 10\mu$ F, $C_0 = 10\mu$ F, L=4.7 μ H, unless otherwise noted.



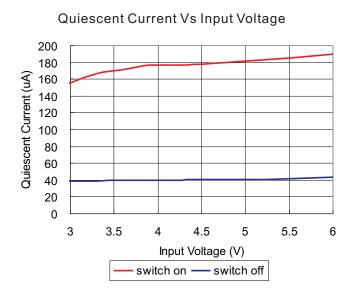


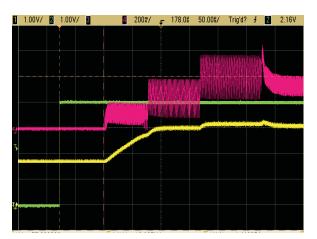
www.poweranalog.com



Typical Performance Characteristics

 $T_A = 25^{\circ}C$, $C_{IN} = 10\mu$ F, $C_0 = 10\mu$ F, L=4.7 μ H, unless otherwise noted.





Start up with Enable



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Application Information

The basic PAM2804 application circuit is shown in Page 1. External component selection is determined by the load requirement, selecting L first and then Cin and Cout.

Inductor Selection

For most applications, the value of the inductor will fall in the range of 1μ H to 4.7μ H. Its value is chosen based on the desired ripple current. Large value inductors lower ripple current and small value inductors result in higher ripple currents. Higher V_{IN} or Vout also increases the ripple current as shown in equation 1. A reasonable starting point for setting ripple current is $\Delta I_L = 400$ mA (40% of 1A).

$$\Delta I_{L} = \frac{1}{(f)(L)} V_{OUT} \left(1 - \frac{V_{OUT}}{V_{IN}} \right)$$
(1)

The DC current rating of the inductor should be at least equal to the maximum load current plus half the ripple current to prevent core saturation. Thus, a 1.4A rated inductor should be enough for most applications (1A + 400mA). For better efficiency, choose a low DC-resistance inductor.

C_{IN} and C_{OUT} Selection

In continuous mode, the source current of the top MOSFET is a square wave of duty cycle Vout/Vin. To prevent large voltage transients, a low ESR input capacitor sized for the maximum RMS current must be used. The maximum RMS capacitor current is given by:

CIN required IRMS
$$\cong IOMAX \frac{\left[VOUT(VIN - VOUT)\right]^{\frac{1}{2}}}{VIN}$$

This formula has a maximum at $V_{IN} = 2Vout$, where $I_{RMS} = I_{OUT}/2$. This simple worst-case condition is commonly used for design because even significant deviations do not offer much relief. Note that the capacitor manufacturer's ripple current ratings are often based on 2000 hours of life. This makes it advisable to further derate the capacitor, or choose a capacitor rated at a higher temperature than required. Consult the manufacturer if there is any question.

The selection of Cout is driven by the required effective series resistance (ESR).

Typically, once the ESR requirement for Cout has been met, the RMS current rating generally

far exceeds the $I_{RIPPLE}(P-P)$ requirement. The output ripple \triangle Vout is determined by:

$$V$$
VOUT \cong VIL $\left($ ESR+ $\frac{1}{8fC_{OUT}}\right)$

Where f = operating frequency, C_{out} =output capacitance and ΔI_{L} = ripple current in the inductor. For a fixed output voltage, the output ripple is highest at maximum input voltage since ΔI_{L} increases with input voltage.

Using Ceramic Input and Output Capacitors

Higher values, lower cost ceramic capacitors are now becoming available in smaller case sizes. Their high ripple current, high voltage rating and low ESR make them ideal for switching regulator applications. Using ceramic capacitors can achieve very low output ripple and small circuit size.

When choosing the input and output ceramic capacitors, choose the X5R or X7R dielectric formulations. These dielectrics have the best temperature and voltage characteristics of all the ceramics for a given value and size.

Thermal consideration

Thermal protection limits power dissipation in the PAM2804. When the junction temperature exceeds 150°C, the OTP (Over Temperature Protection) starts the thermal shutdown and turns the pass transistor off. The pass transistor resumes operation after the junction temperature drops below 120°C.

For continuous operation, the junction temperature should be maintained below 125°C. The power dissipation is defined as:

$$P_{D} = I_{O}^{2} \frac{V_{O}R_{DSONH} + (V_{IN} - V_{O})R_{DSONL}}{V_{IN}} + (t_{SW}F_{S}I_{O} + I_{Q})V_{IN}$$

 I_{α} is the step-down converter quiescent current. The term tsw is used to estimate the full load step-down converter switching losses.



Application Information

For the condition where the step-down converter is in dropout at 100% duty cycle, the total device dissipation reduces to:

$$\mathsf{P}_{\mathsf{D}} = \mathsf{I}_{\mathsf{O}}^{2} \mathsf{R}_{\mathsf{DSONH}} + \mathsf{I}_{\mathsf{Q}} \mathsf{V}_{\mathsf{IN}}$$

Since $R_{DS(ON)}$, quiescent current, and switching losses all vary with input voltage, the total losses should be investigated over the complete input voltage range. The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of surrounding airflow and temperature difference between junction and ambient. The maximum power dissipation can be calculated by the following formula:

$$P_{D} = \frac{T_{J(MAX)} - T_{A}}{\theta_{JA}}$$

Where TJ(max) is the maximum allowable junction temperature $125^{\circ}C.T_{A}$ is the ambient temperature and θ_{JA} is the thermal resistance from the junction to the ambient. Based on the standard JEDEC for a two layers thermal test board, the thermal resistance θ_{JA} of SOT23-5 package is 250°C/W. The maximum power dissipation at $T_{A} = 25^{\circ}C$ can be calculated by following formula:

P_D=(125°C-25°C)/250°C/W=0.4W

Setting the Output Current

The internal feedback(FB) voltage is 0.1V (Typical). The output current is calculated as below:

ILED=0.1/Rs

The output Current is given by the following table.

Rs(Ω)	ILED(mA)
0.286	350
0.143	700
0.1	1000

As the input voltage approaches the LED forward voltage, the PAM2804 turns the P-channel transistor continuously on. In this mode the Voltage drop on LED is equal to the input voltage minus the voltage drop across the P - channel transistor, Inductor and current resistor:

$$V_{\text{LEDDROP}} = V_{\text{IN}} - \text{ILED} (R_{\text{dson}} + R_{\text{L}} + R_{\text{s}})$$

where R_{dson} = P-channel switch ON resistance, ILED = LED current, R_{L} = Inductor DC resistance, R_{s} = Inductor DC resistance.

UVLO and Soft-Start

The feedback and the circuit remain reset until the VIN crosses its UVLO threshold.

The PAM2804 has an internal soft-start circuit that limits the in-rush current during start-up. This prevents possible voltage drops of the input voltage and eliminates the output voltage overshoot. The soft-start acts as a digital circuit to increase the switch current in several steps to the P-channel current limit (1500mA).

Short LED Protection

The switch peak current is limited cycle-by-cycle to a typical value of 1500mA. In the event of an output voltage short circuit, the device operates with a frequency of 500kHz and minimum duty cycle, therefore the average input current is typically 200mA.

Thermal Shutdown

When the die temperature exceeds 150°C, a reset occurs and the reset remains until the temperature decrease to 120°C, at which time the circuit can be restarted.

100% Duty Cycle Operation



Application Information

PCB Layout Check List

When laying out the printed circuit board, the following checklist should be used to ensure proper operation of the PAM2804. These items are also illustrated graphically in Figure 1. Check the following in your layout:

1. The power traces, consisting of the GND trace, the SW trace and the VIN trace should be kept short, direct and wide.

2. Does the V_{FB} pin connect directly to the current sense resistor? The current sense resistor to GND trace should be kept short, direct and wide.

3. Does the (+) plate of CIN connect to VIN as closely as possible? This capacitor provides the AC current to the internal power MOSFETs.

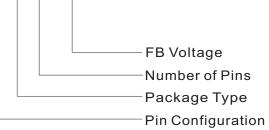
4. Keep the switching node, SW, away from the sensitive VFB node.

5. Keep the (–) plates of C_{IN} and C_{OUT} as close as possible.



Ordering Information

PAM 2804 X X X X



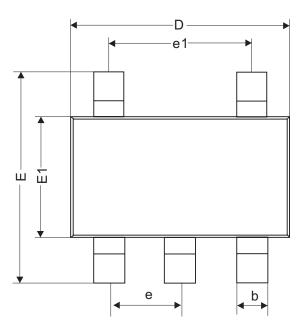
Pin Configuration	Package Type	Number of Pins	FB Voltage
А Туре	A: SOT-23	B: 5	010: 0.1V
1. EN			
2. GND			
3. SW			
4. VIN			
5. FB			

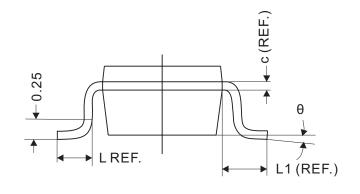
Part Number	Marking	Package Type	Standard Package
PAM2804AAB010	Refer to P2	SOT-23-5	3,000Units/Tape&Reel

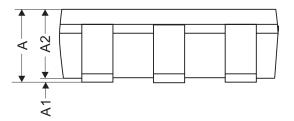


Outline Dimensions

SOT23-5







REF.	Millimeter		
	Min	Max	
A	1.10MAX		
A1	0	0.10	
A2	0.70	1	
С	0.12F	REF.	
D	2.70	3.10	
Е	2.60	3.00	
E1	1.40	1.80	
L	0.45REF.		
L1	0.60REF.		
θ	0°	10°	
b	0.30	0.50	
е	0.95REF.		
e1	1.90REF.		